



IR Receiver Modules for Remote Control Systems



22594

DESCRIPTION

This IR receiver series is optimized for short burst remote control systems in different environments. The customer can choose between different IC settings (AGC variants), to find the optimum solution for his application. The higher the AGC, the better noise is suppressed, but the lower the code compatibility.

The devices contain a PIN diode and a preamplifier assembled on a lead frame. The epoxy package contains an IR filter. The demodulated output signal can be directly connected to a microprocessor for decoding. These components have not been qualified to automotive specifications.

FEATURES

- Individual IC settings to reach maximum performance
- Immunity against noise (lamps, LCD TV, Wi-Fi)
- Low supply current
- Photo detector and preamplifier in one package
- Supply voltage: 2.0 V to 5.5 V
- Material categorization:
for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

LINKS TO ADDITIONAL RESOURCES



Product Page



Marking

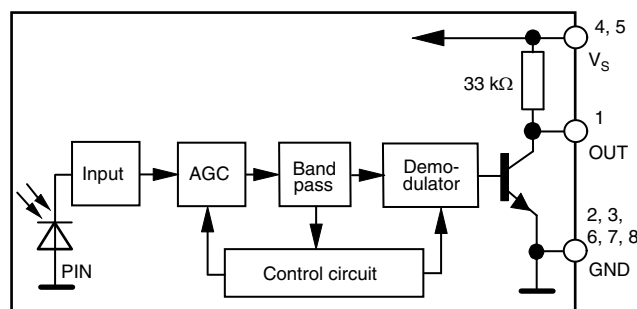
APPLICATIONS

- Infrared remote control systems

DESIGN SUPPORT TOOLS

- [3D models](#)
- [Window size calculator](#)

BLOCK DIAGRAM



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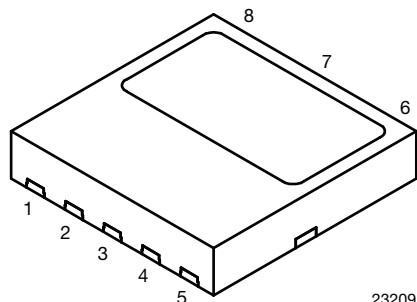
TSOP573..H, TSOP575..H

Vishay Semiconductors

MECHANICAL DATA

Pinning:

1 = OUT, 2, 3, 6, 7, 8 = GND, 4, 5 = V_S



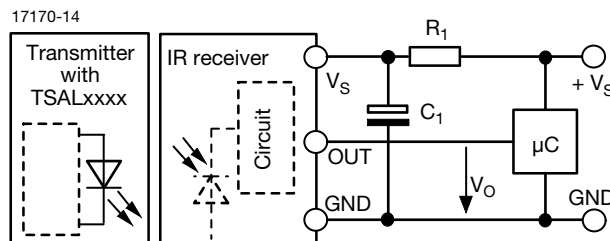
23209

ORDERING CODE

Taping:

TSOP57...HTT1 - top view taped, 1500 pcs/reel

APPLICATION CIRCUIT



R_1 and C_1 recommended in case there are strong ripple or spikes on the supply line.

PARTS TABLE

AGC		NOISY ENVIRONMENTS AND SHORT BURSTS (AGC3)	VERY NOISY ENVIRONMENTS AND SHORT BURSTS (AGC5)
Carrier frequency	36 kHz	TSOP57336H ⁽¹⁾⁽²⁾	TSOP57536H
	38 kHz	TSOP57338H ⁽³⁾⁽⁵⁾	TSOP57538H
	40 kHz	TSOP57340H	TSOP57540H
	56 kHz	TSOP57356H ⁽⁴⁾	TSOP57556H
Package		Belobog shield	
Pinning		1 = OUT, 2, 3, 6, 7, 8 = GND, 4, 5 = V_S	
Dimensions (mm)		3.95 W x 3.95 H x 0.8 D	
Mounting		SMD	
Application		Remote control	
Best choice for		⁽¹⁾ MCIR ⁽²⁾ RCMM ⁽³⁾ RECS-80 Code ⁽⁴⁾ r-map ⁽⁵⁾ XMP	
Special options		Extended temperature range: www.vishay.com/doc?82738	

ABSOLUTE MAXIMUM RATINGS

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Supply voltage		V_S	-0.3 to +6	V
Supply current		I_S	5	mA
Output voltage		V_O	-0.3 to ($V_S + 0.3$)	V
Output current		I_O	5	mA
Junction temperature		T_j	100	°C
Storage temperature range		T_{stg}	-25 to +85	°C
Operating temperature range		T_{amb}	-25 to +85	°C
Power consumption	$T_{amb} \leq 85^\circ\text{C}$	P_{tot}	10	mW

Note

- Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect the device reliability



ELECTRICAL AND OPTICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage		V_S	2.0	-	5.5	V
Supply current	$V_S = 3.3\text{ V}$, $E_v = 0$	I_{SD}	0.25	0.35	0.45	mA
	$E_v = 40\text{ klx}$, sunlight	I_{SH}	-	0.8	-	mA
Transmission distance	$E_v = 0$, IR diode TSAL6200, $I_F = 50\text{ mA}$, test signal see Fig. 1	d	-	18	-	m
Output voltage low	$I_{OSL} = 0.5\text{ mA}$, $E_e = 0.7\text{ mW/m}^2$, test signal see Fig. 1	V_{OSL}	-	-	100	mV
Minimum irradiance	Test signal: RC5 code	$E_{e\text{ min.}}$	-	0.2	0.4	mW/m^2
	Test signal: XMP code	$E_{e\text{ min.}}$	-	0.35	0.6	mW/m^2
Maximum irradiance	Pulse width tolerance: $t_{pi} - 3/f_0 < t_{po} < t_{pi} + 3.5/f_0$, test signal see Fig. 1	$E_{e\text{ max.}}$	30	-	-	W/m^2
Directivity	Angle of half transmission distance	$\phi_{1/2}$	-	± 75	-	deg

TYPICAL CHARACTERISTICS ($T_{amb} = 25^{\circ}\text{C}$, unless otherwise specified)

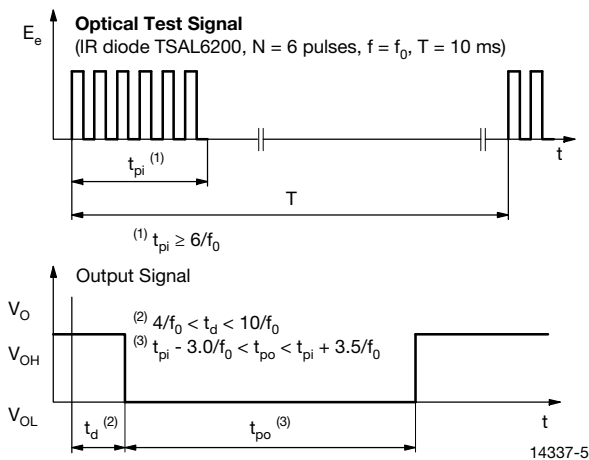


Fig. 1 - Output Active Low

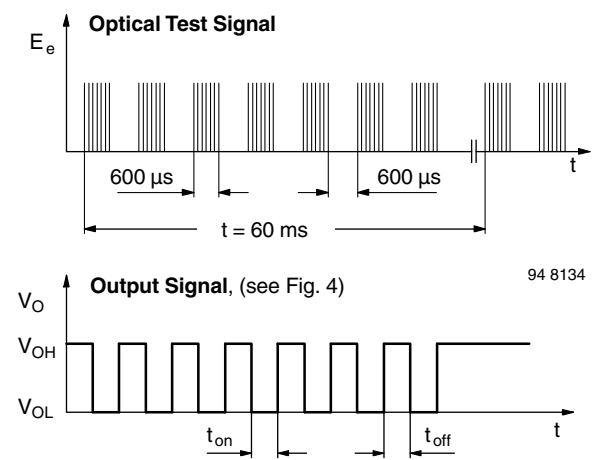


Fig. 3 - Output Function

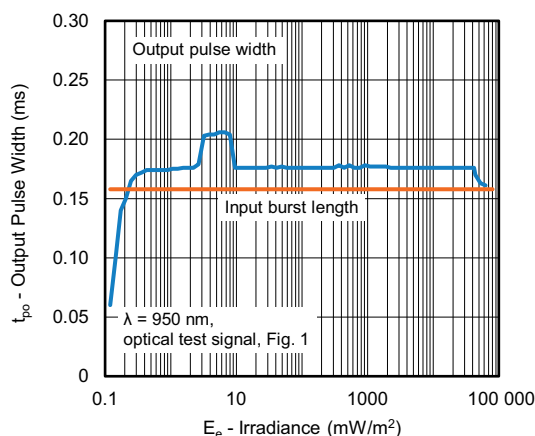


Fig. 2 - Pulse Length and Sensitivity in Dark Ambient

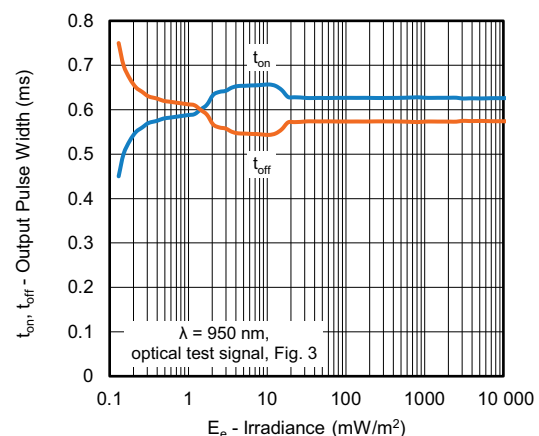


Fig. 4 - Output Pulse Diagram

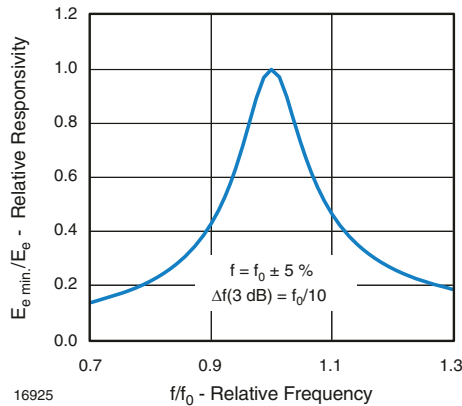


Fig. 5 - Frequency Dependence of Responsivity

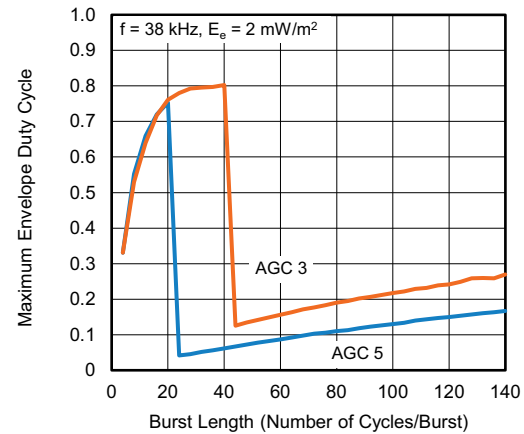


Fig. 8 - Max. Envelope Duty Cycle vs. Burst Length

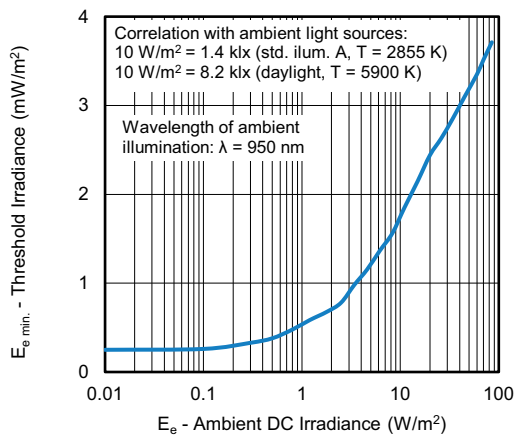


Fig. 6 - Sensitivity in Bright Ambient

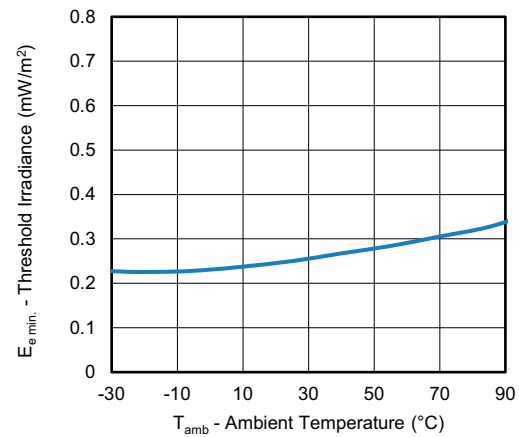


Fig. 9 - Sensitivity vs. Ambient Temperature

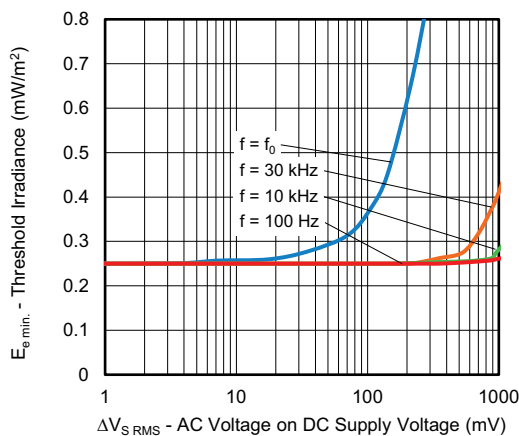


Fig. 7 - Sensitivity vs. Supply Voltage Disturbances

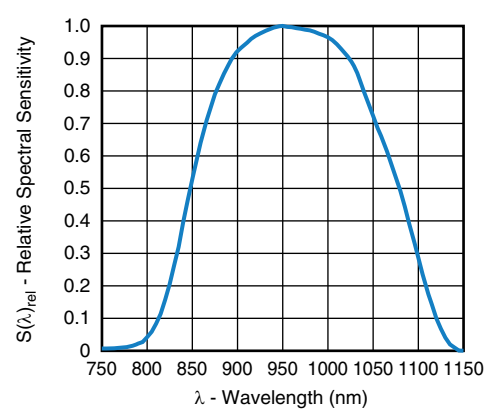


Fig. 10 - Relative Spectral Sensitivity vs. Wavelength

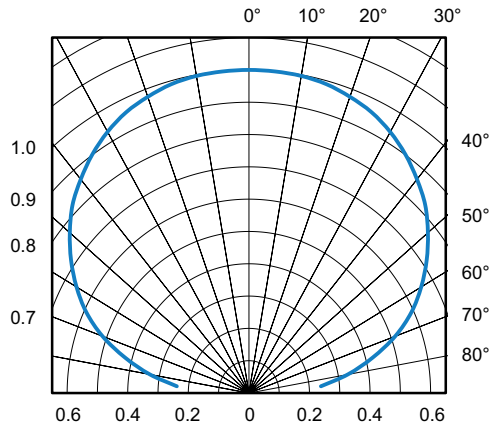


Fig. 11 - Horizontal Directivity

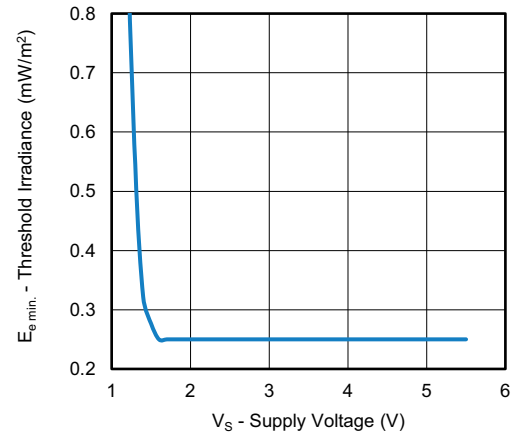


Fig. 12 - Sensitivity vs. Supply Voltage

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SUITABLE DATA FORMAT

The TSOP573.., TSOP575.. series is designed to suppress spurious output pulses due to noise or disturbance signals. The devices can distinguish data signals from noise due to differences in frequency, burst length, and envelope duty cycle. The data signal should be close to the device's band-pass center frequency (e.g. 38 kHz) and fulfill the conditions in the table below.

When a data signal is applied to the TSOP573.., TSOP575.. in the presence of a disturbance, the sensitivity of the receiver is automatically reduced by the AGC to insure that no spurious pulses are present at the receiver's output. Some examples which are suppressed are:

- DC light (e.g. from tungsten bulbs sunlight)
- Continuous signals at any frequency
- Strongly or weakly modulated patterns from fluorescent lamps with electronic ballasts (see Fig. 13 or Fig. 14)
- 2.4 GHz and 5 GHz Wi-Fi

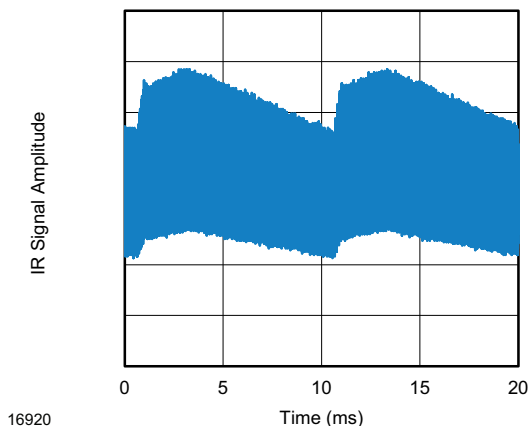


Fig. 13 - IR Signal from Fluorescent Lamp With Low Modulation

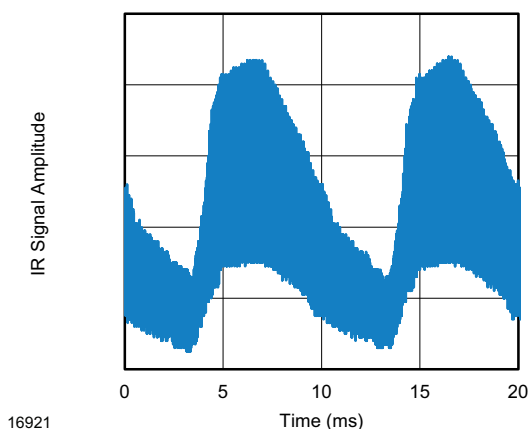


Fig. 14 - IR Signal from Fluorescent Lamp With High Modulation

	TSOP573..	TSOP575..
Minimum burst length	6 cycles/burst	6 cycles/burst
After each burst of length a minimum gap time is required of	6 to 40 cycles ≥ 7 cycles	6 to 20 cycles ≥ 7 cycles
For bursts greater than a minimum gap time in the data stream is needed of	40 cycles > 6 x burst length	20 cycles > 10 x burst length
Maximum number of continuous short bursts/second	2500	2500
RCMM code	Preferred	Yes
r-map code	Preferred	Yes
XMP code	Preferred	Yes
Suppression of interference from fluorescent lamps	Mild and complex disturbance patterns are suppressed (example: signal pattern of Fig. 13 and Fig. 14)	Critical disturbance patterns are suppressed, e.g. highly dimmed LCDs

Note

- For data formats with long bursts (more than 10 carrier cycles) please see the datasheet for TSOP572.., TSOP574..

Technical drawing of a rectangular mold assembly. The main view shows a top-down perspective of a rectangular mold with internal features. Dimensions are provided in millimeters (mm) and include tolerances. Key dimensions include:

- Overall width: $4 \times 0.75 = 3$
- Overall height: 1.8 (with a tolerance of 0.3)
- Internal width: 0.75 ± 0.05
- Internal height: 0.475
- Internal width (bottom): 0.35 ± 0.05 (with a tolerance of 0.4)
- Internal height (bottom): 0.55
- Internal width (bottom): 1.5
- Internal height (bottom): 0.3
- Internal width (bottom): 3
- Internal height (bottom): 2.85
- Internal width (bottom): 0.3
- Internal height (bottom): 0.55
- Internal width (bottom): 1 ± 0.2
- Internal height (bottom): 0.15
- Internal width (bottom): 0.1

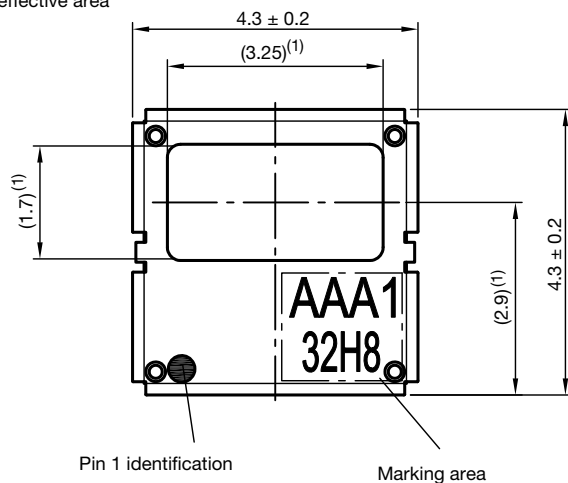
A cross-section view is shown below the main view, indicating a trapezoidal profile. The cross-section is labeled with a trapezoid symbol and the value 0.1 .

Technical specifications and notes:

- Outer edge to solder molded ± 0.1 mm
- technique according to specifications
- All dimensions in mm

technical drawings
according to DIN
specifications

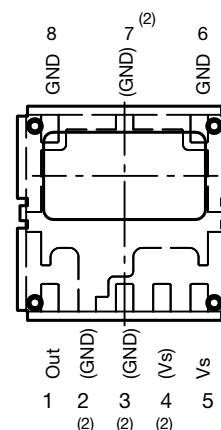
(1) optically effective area



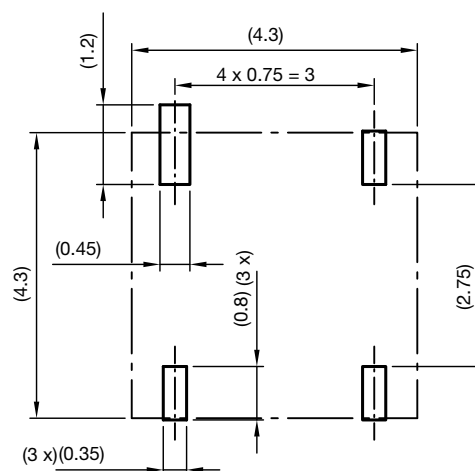
Technical drawing of a vertical cabinet with a door and a handle. A dimension line indicates a height of 0.1 meters.

(2) Pins connected internally.
It is not necessary to connect externally.

Pinning from Topview



Proposed pad layout from
component side
(dim. for reference only)

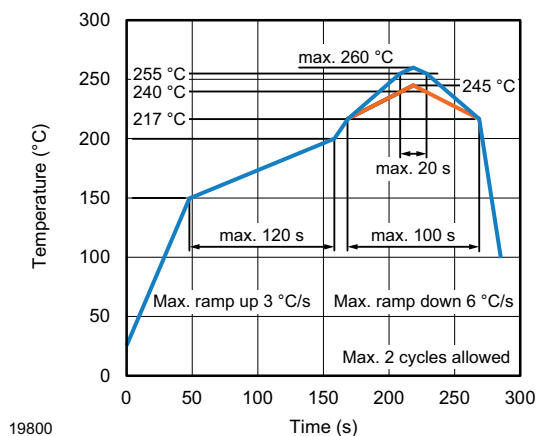


**ASSEMBLY INSTRUCTIONS****Reflow Soldering**

- Reflow soldering must be done within 168 h while stored under a max. temperature of 30 °C, 60 % RH after opening the dry pack envelope
- Set the furnace temperatures for pre-heating and heating in accordance with the reflow temperature profile as shown in the diagram. Exercise extreme care to keep the maximum temperature below 260 °C. The temperature shown in the profile means the temperature at the device surface. Since there is a temperature difference between the component and the circuit board, it should be verified that the temperature of the device is accurately being measured
- Handling after reflow should be done only after the work surface has been cooled off

Manual Soldering

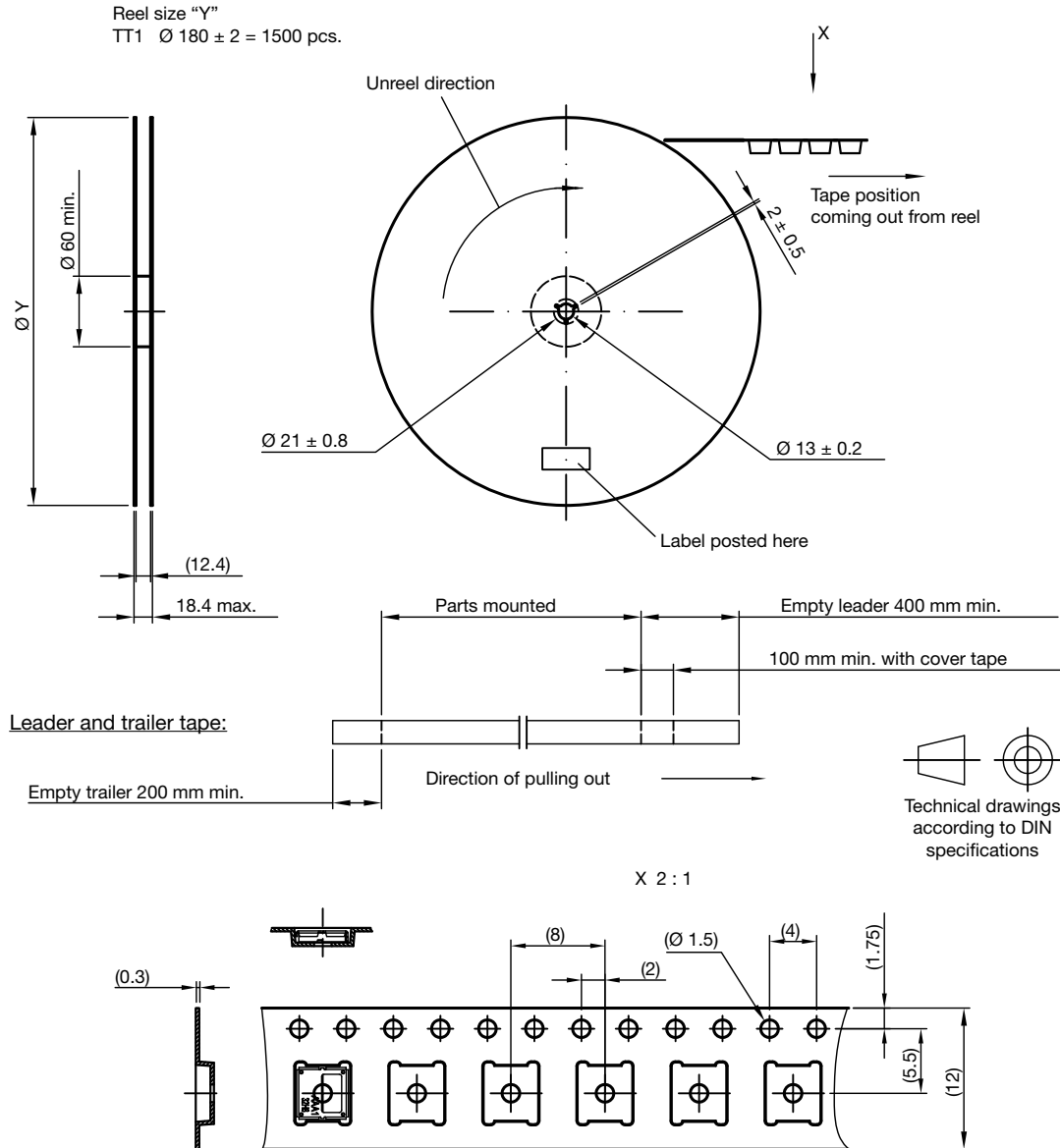
- Use a soldering iron of 25 W or less. Adjust the temperature of the soldering iron below 300 °C
- Finish soldering within 3 s
- Handle products only after the temperature has cooled off

VISHAY LEAD (Pb)-FREE REFLOW SOLDER PROFILE



TAPING VERSION TSOP57... DIMENSIONS in millimeters

Tape and reel dimensions:

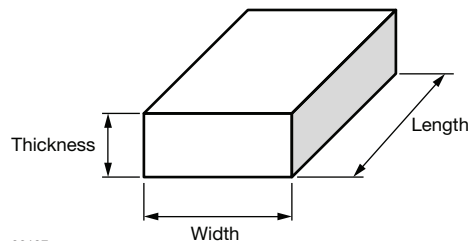


Drawing-No.: 9.700-5380.01-4
Issue: 3; 07.03.18

Not indicated tolerances ± 0.1

**OUTER PACKAGING**

The sealed reel is packed into a pizza box.

CARTON BOX DIMENSIONS in millimeters

	THICKNESS	WIDTH	LENGTH
Pizza box (Panhead, Heimdall, and Belobog) (taping in reels)	50	340	340

LABEL**Standard bar code labels for finished goods**

The standard bar code labels are product labels and used for identification of goods. The finished goods are packed in final packing area. The standard packing units are labeled with standard bar code labels before transported as finished goods to warehouses. The labels are on each packing unit and contain Vishay Semiconductor GmbH specific data.

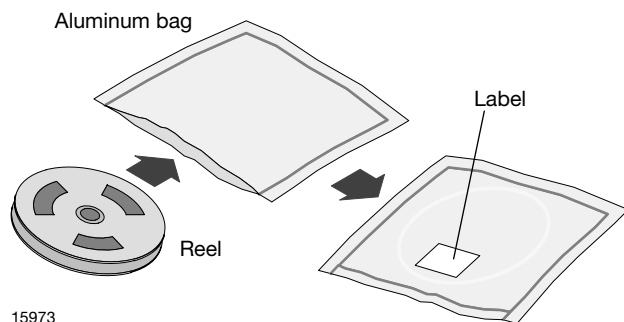
VISHAY SEMICONDUCTOR GmbH STANDARD BAR CODE PRODUCT LABEL (finished goods)

PLAIN WRITING	ABBREVIATION	LENGTH
Item-description	-	18
Item-number	INO	8
Selection-code	SEL	3
LOT-/serial-number	BATCH	10
Data-code	COD	3 (YWW)
Plant-code	PTC	2
Quantity	QTY	8
Accepted by	ACC	-
Packed by	PCK	-
Mixed code indicator	MIXED CODE	-
Origin	xxxxxxx+	Company logo
LONG BAR CODE TOP	TYPE	LENGTH
Item-number	N	8
Plant-code	N	2
Sequence-number	X	3
Quantity	N	8
Total length	-	21
SHORT BAR CODE BOTTOM	TYPE	LENGTH
Selection-code	X	3
Data-code	N	3
Batch-number	X	10
Filter	-	1
Total length	-	17



DRY PACKING

The reel is packed in an anti-humidity bag to protect the devices from absorbing moisture during transportation and storage.



15973

FINAL PACKING

The sealed reel is packed into a cardboard box.

RECOMMENDED METHOD OF STORAGE

Dry box storage is recommended as soon as the aluminum bag has been opened to prevent moisture absorption. The following conditions should be observed, if dry boxes are not available:

- Storage temperature 10 °C to 30 °C
- Storage humidity ≤ 60 % RH max.

After more than 168 h under these conditions moisture content will be too high for reflow soldering.

In case of moisture absorption, the devices will recover to the former condition by drying under the following condition:

192 h at 40 °C + 5 °C / - 0 °C and < 5 % RH (dry air / nitrogen) or

96 h at 60 °C + 5 °C and < 5 % RH for all device containers or 24 h at 125 °C + 5 °C not suitable for reel or tubes.

An EIA JEDEC® standard J-STD-020 level 3 label is included on all dry bags.

Caution		LEVEL 3
This bag contains MOISTURE-SENSITIVE DEVICES		
1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)		
2. Peak package body temperature: <u>260</u> °C If blank, see adjacent bar code label		
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be		
a) Mounted within: <u>168</u> hours of factory conditions If blank, see adjacent bar code label		
b) Stored per J-STD-033		
4. Devices require bake, before mounting, if:		
a) Humidity Indicator Card reads >10% for level 2a - 5a devices or >60% for level 2 devices when read at 23±5°C		
b) 3a or 3b are not met		
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure		
Bag Seal Date: _____ If blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		

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EIA JEDEC standard J-STD-020 level 3 label is included on all dry bags

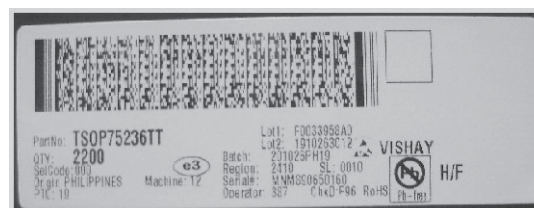
ESD PRECAUTION

Proper storage and handling procedures should be followed to prevent ESD damage to the devices especially when they are removed from the antistatic shielding bag. Electrostatic sensitive devices warning labels are on the packaging.

VISHAY SEMICONDUCTORS STANDARD BAR CODE LABELS

The Vishay Semiconductors standard bar code labels are printed at final packing areas. The labels are on each packing unit and contain Vishay Semiconductors specific data.

BAR CODE PRODUCT LABEL (example)



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